	1	2	3		4	5		6
A								A
							MIN. TRACK W	DESIGN INFORMATION
В							MIN. CLEARAN MIN. VAA PAD MINIMUKA NR VAA PAD PER IPC-D-275 REGISTRATION TOLERA MATERIAL: FR-408 X THICKNESS: X 62 MI TOLERANCE: BOW & TWIST: X DRILING: REFERENCE: X A PTH MIN COPPER THK	ICE: 0.2 mm
с							SOLDER RESIST COL X GRI SURFACE FINISH: X MM. TIN/SILVER ARRAY/PANEL:	EEN BLUE OTHER MMERSION GOLD (ENG) ENEPIG OR EQUIV OTHER CUT AND TRIM PER MECH LAYER 1 N.C. ROUTE X V. SCORE
	The PMP10175 PCB is the same as the PCB for TI's PMP10143 design						CERTFICATION: MATERALS AND WORKMANSHP FOR ALL PCBS TO MEET OR EXCEED THE REQUREMENTS OF: X ANS IPC-A-600F CLASS -> 1 X 2 3 X UL 94V-0 X RoHS OTHER <u>PER ORDER</u> ADDITIONAL REQUREMENTS: MICROSECTION: YES BARE BOARD ELC. TEST: NONE X REQURED PER ORDER	
							MANUFACTURER'S UL: RAL METAL X SUK	
D	COMPONENTS MARK ASSEMBLY VARIAN	KED 'DNP' SHOULD NOT BE POPULATED. IT: [No Variations] BOARD #: PMP10143 REV: A		Texas Instruments (TD and/or its licensors do not varrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not varrant that this design will meet			Public Release D RE NAME: PMPI0143 Rev_A PCB.PcbDoc DXMEER LAYOUT BY:	
	PLOT NAME = 1	16.07.2015 13:39:26 2	SUN REU: Not In VersionControl TEXAS INSTRUMENTS 3	the specifications, wil an implementation. TI a	l be suitable for your application or fit ind/or its licensors do not warrant that t	o not uarrant that this design uill meet for any particular purpose, or uill operate in the design is production uorthy. You should rm the system functionality for your applicatio 5		R. Scibilia ALTUM DESONER VERSON: 14.3.18.45973 6

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